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UTILITY PATENT APPLICATION TRANSMITTAL (Only for new nonprovisional applications under 37 CFR 1.53(b))	Attorney Docket No. 98 P 5548	Total Pages
	First Named Inventor or Application Identifier	
	Andreas HUBER, Franz FORSTER, Peter NIEDERMEIER and Walter LIMMER	
Express Mail Label No.		

APPLICATION ELEMENTS See MPEP chapter 600 concerning utility patent application contents.	ADDRESS TO: Assistant Commissioner for Patents Box Patent Application Washington, DC 20231
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1. ☒ Fee Transmittal Form
(Submit an original, and a duplicate for fee processing)
2. ☒ Specification [Total Pages 10] 1
(preferred arrangement set forth below)
 - Descriptive title of the invention
 - Cross References to Related Applications
 - Statement Regarding Fed sponsored R & D
 - Reference to Microfiche Appendix
 - Background of the invention
 - Brief Summary of the invention
 - Brief Description of the Drawings (if filed)
 - Detailed Description
 - Claim(s)
 - Abstract of the Disclosure
3. ☒ Drawing(s) (35 USC 113) [Total Sheets 3] 1
4. Oath or Declaration [Total Pages 1] 1
 - a. ☒ Newly executed (original or copy)
 - b. ☐ Copy from a prior application (37 CFR 1.63(d))
(for continuation/divisional with Box 17 completed)
[Note Box 5 below]
 - i. ☐ **DELETION OF INVENTOR(S)**
Signed statement attached deleting inventor(s) named in the prior application, see 37 CFR 1.63(d)(2) and 1.33(b).
5. ☐ Incorporation By Reference (useable if Box 4b is checked)
The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied under Box 4b, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.

6. ☐ Microfiche Computer Program (Appendix)
7. Nucleotide and/or Amino Acid Sequence Submission (if applicable, all necessary)
 - a. ☐ Computer Readable Copy
 - b. ☐ Paper Copy (identical to computer copy)
 - c. ☐ Statement verifying identity of above copies

ACCOMPANYING APPLICATION PARTS	
8. <input checked="" type="checkbox"/>	Assignment Papers (cover sheet & document(s))
9. <input type="checkbox"/>	37 CFR 3.73(b) Statement (when there is an assignee) <input type="checkbox"/> Power of Attorney
10. <input type="checkbox"/>	English Translation Document (if applicable)
11. <input checked="" type="checkbox"/>	Information Disclosure Statement (IDS)/PTO-1449 <input checked="" type="checkbox"/> Copies of IDS Citations
12. <input checked="" type="checkbox"/>	Preliminary Amendment
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14. <input type="checkbox"/>	Small Entity <input type="checkbox"/> Statement filed in prior application, Status still proper and desired
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17. If a CONTINUING APPLICATION, check appropriate box and supply the requisite information:

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IN THE UNITED STATES PATENT
AND TRADEMARK OFFICE

In re Application of

Andreas HUBER
Franz FORSTER
Peter NIEDERMEIER
Walter LIMMER

Serial No:

Art Unit:

Filed: 26 August 1999

Examiner

For: THERMALLY CONDUCTIVE INLAY MAT FOR
ELECTRICAL AND ELECTRONIC APPLIANCES

PRELIMINARY AMENDMENT

Assistant Commissioner For Patents
Washington, D.C. 20231


Sir:

Prior to calculation of the filing fee please amend
the claims in the above-identified application as follows:

IN THE CLAIMS:

In claim 8 line 6, change "one of the preceding
claims" to --Claim 1--.

Respectfully submitted,

By: 
Robert F. Hargest
Attorney for Applicant
Registration No. 25,590

26 August 1999

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Prior art

Hitherto, the following principle has been used to prevent a buildup of heat in electrical appliances: at least part of the appliances is embedded in a potting compound with good thermal conductivity. For example, the document EP-A 645 944 has disclosed an operating device for electric lamps in which the heat is dissipated through a thermally conductive potting compound. This compound transmits the heat to the housing walls, where it can be dissipated to the environment.

Summary of the invention

The object of the present invention is to provide a thermally conductive inlay mat for electrical and electronic appliances in accordance with the preamble of claim 1, which can be used to dissipate the heat in these appliances in a particularly simple manner.

This object is achieved by means of the distinguishing features of claim 1. Particularly advantageous refinements are given in the dependent claims.

The thermally conductive inlay mat for electrical and electronic appliances has a base body of simple, sheet-like geometry, an underside being intended to be in contact with the outer wall of the appliance and a top side of the base body being intended to be in contact with the heat source inside the appliance. Preferably, the top side is provided with a height-compensating structure, while the underside may be smooth. A suitable material is a material with a low Shore hardness of at most 15. In a particularly preferred embodiment, modified hydrocarbon resin or silicone composite sheet is used.

The introduction of the newly developed mat allows the heat loss in such appliances to be transmitted particularly reliably and effectively from the heat source to an external wall of the appliance. By way of example, the heat source is an electronic component on a circuit board. When the mat (minimum thickness 1 mm) has been laid between circuit board and appliance wall, it is possible to dissipate the heat loss via the underside of the circuit board and to transmit this heat to the appliance wall, in particular a base plate, without having to take any account of the position of electronic components, for example SMD components, on the underside of the circuit board. Advantageously, the mat has a special structure on its surface facing toward the electrical or electronic components, which structure makes it possible to compensate for the different heights of various components. Raised lamellae which are arranged parallel to one another are, for example, eminently suitable. Typically, a mat of this nature makes it possible to compensate for approx. 3 mm without its heat-dissipating function being impaired. This inlay mat preferably comprises electrically insulating material, such as plastic or ceramic, in particular synthetic resin, such as modified hydrocarbon resin, for example Guronic-FR produced by Paul Jordan, or silicone composite sheets, for example KU-TKC or KU-TKM produced by Kunze Folien, which are filled with ceramic in order to increase the thermal conductivity still further. Mats made from homogeneous synthetic resin are deformable, flexible and have a soft and sticky consistency, and may exhibit a high level of electrical insulation. The said materials can be cast in any desired shapes and are therefore readily able to meet the requirements imposed with regard to shape.

This mat is of simple geometric shape (e.g. rectangular) and its thickness is expediently dimensioned suitably for the distance between heat

source and appliance wall, for example between circuit board and base plate of an appliance. A thickness of from 1 to 10 mm is well suited in practice. In particular, synthetic resin is a soft and yielding material. A height-compensating structure on at least one surface allows good thermal contact to be achieved even for different heights of various electronic components.

Advantageously, the mat has raised lamellae on at least the top side, which faces toward the circuit board, which lamellae leave sufficient space to accommodate projections on the electronic components. A rectangular or trapezoidal cross section of the lamellae is eminently suitable. The base width of and the distance between the lamellae should be of approximately the same order of magnitude (factor 1:2 to 2:1). The distance between and the height of the lamellae is preferably between 1 and 8 mm. These dimensions ensure good thermal contact with conventional electronic components, which are of approximately the same size.

Particular advantages compared to a potting compound are that it is possible for the appliance to be opened again, that the mechanical load caused by different coefficients of thermal expansion is lower, and that less material is consumed. The thickness of the inlay mat is dimensioned in such a way that the inlay mat is in as good contact with the heat source as possible (the heat source is in particular the underside of the circuit board).

Further advantages consist in the fact that the improved dissipation of heat in the appliances fitted with the inlay mat extends the possible applications of such appliances to environments which are subjected to high thermal loads. This applies, for example, to operating devices of electric lamps, which are then suitable even for thermally disadvantageous luminaire

structures. Moreover, appliances of this nature are more suitable for recycling and are better able to satisfy the conditions of electronic scrap regulations. Furthermore, it is now possible to rework these appliances during manufacture.

It is also possible to use a plurality of inlay mats in one electronic appliance. This is advisable, for example, if a plurality of electronic circuit boards are used in the appliance with different orientations.

Figures

The invention will be explained in more detail below with reference to an exemplary embodiment. In the drawings:

Figure 1 shows an inlay mat in plan view (Figure 1a), in longitudinal section (Figure 1b) and in cross section (Figure 1c)

Figure 2 shows an operating device for a discharge lamp in side view and partially in section

Figure 3 shows the operating device from Figure 2 with the top part removed.

Description of the drawings

Fig. 1 shows an approximately rectangular inlay mat 3 with a length of 11 cm, a width of 7.5 cm and a total thickness of 4.5 mm. Mutually parallel, longitudinally oriented lamellae 6 of rectangular cross section with a height of 2.5 mm and a width of approximately 1 mm are arranged on the top side, which faces toward the heat source, on a base body 5 with a thickness of 2 mm. The underside 4 is smooth and thus provides optimum thermal contact with the appliance wall. The lamellae 6 are spaced apart by approximately 3 mm in each case. The

overall result is a structure with a sawtooth or meandering cross section (Figure 1c). The mat 3 has indents 8 at its four corners and also a central hole 9, which together make it easier to hold and align the mat 3 in the appliance or form recesses for attachment means. The mat comprises modified hydrocarbon resin which makes the mat sticky at its surface. The Shore A hardness is 10. The mat therefore has good adhesion to the base plate and very good thermal contact with the circuit board.

An additional film 7 (cf. Figures 2 and 3) made from plastic (Hostafen), which is arranged between mat and base plate, makes it possible to ensure electrical insulation between circuit board and base part even in the unlikely event of a component penetrating through the mat or of current being fed through the mat to the wall of the appliance. If the thickness of the film 7 is 0.1 mm, the result, in the installed state, is therefore an overall thickness of 4.6 mm.

Figure 2 shows an operating device for a high-pressure discharge lamp as an exemplary embodiment of an electronic appliance. For this device, an electronic ballast 10 is used with a housing made from plastic and metal. This housing is divided into a metal base plate 12 made from aluminum and a top part 11 made from plastic, comprising a cover 13 with attached side walls 14. A horizontal electronic circuit board 15 (shaded), which is surrounded by the housing and on which the electronic components (not shown) are mounted, is attached to the base plate 12 by means of screws 20. In addition, an on-edge circuit board (not visible) is mounted in the interior 25 of the housing. An inlay mat 3 with good thermal conductivity is laid between circuit board 15 and base plate 12. On one of the side walls, there is a connection part 16 which is screwed to the base plate 12 and is used for electrically

connecting the lamp to the operating device and to supply the operating device with voltage.

After the mounting circuit board 15, including the electronic and electrical components which are arranged thereon, has been attached to the base plate 12, the top part 11 is fitted onto the base plate 12 and is locked to the circuit board 15 by means of a snap-action connection 18. The dimensions of the mat 3 are slightly smaller than those of the circuit board 15, so that there is no need to provide a special recess on the mat 3 for the snap-action mechanism which is located at the outer edge of the circuit board.

Fig. 3 shows the electronic ballast without the surrounding cover or side wall. In addition to the horizontal circuit board 15, the electronic ballast also has a circuit board 17 which is positioned on edge. The distance between the horizontal circuit board 15 and the base plate 12 is 4.5 mm. In this way, it is ensured that the inlay mat 3 is always in thermally conductive contact both with the circuit board 15 and with the base plate 12.

The geometry of the mat is adapted to the geometry of the base plate. A further mat of this nature may also be inserted between the on-edge circuit board 17 and the adjoining side wall.

A comparison with an identical operating device which, however, was provided with conventional potting compound revealed a considerable improvement in the maximum permissible ambient temperature for the luminaire of 15°C. While previous luminaires were only able to tolerate an ambient temperature of 25°C, they are now able to withstand a load of up to 40°C.

Claims

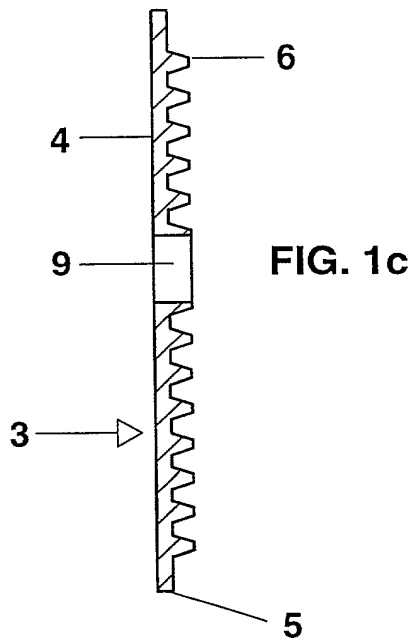
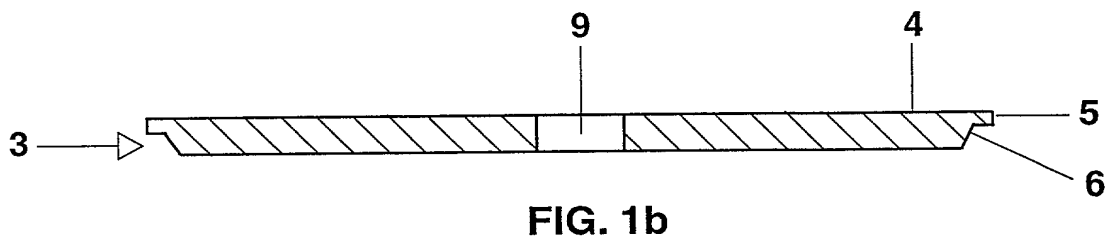
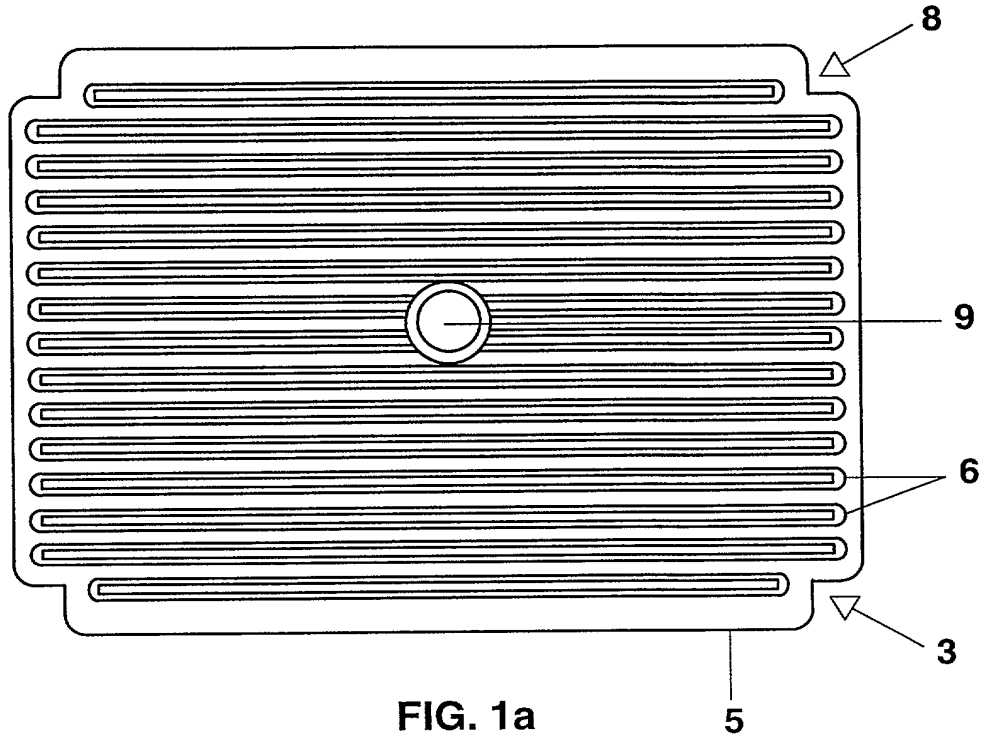
1. A thermally conductive inlay mat (3) for
electrical and electronic appliances, having a
5 base body (5) of simple sheet-like geometry, an
underside (4) of the base body being intended to
be in contact with the outer wall of the appliance
and a top side of the base body being intended to
be in contact with the heat source inside the
10 appliance.
2. The inlay mat as claimed in claim 1, wherein the
mat (3) comprises modified hydrocarbon resin or a
silicone composite sheet.
- 15 3. The inlay mat as claimed in claim 1, wherein the
mat (3) comprises electrically insulating
material, in particular homogeneously comprises
synthetic resin.
- 20 4. The inlay mat as claimed in claim 1, wherein the
thickness of the mat (3) is at least 1 mm.
5. The inlay mat as claimed in claim 1, wherein the
25 underside (4) is smooth, while the top side has a
height-compensating structure.
6. The inlay mat as claimed in claim 5, wherein the
height-compensating structure comprises raised
30 lamellae (6).
7. The inlay mat as claimed in claim 1, wherein the
mat (3) has a sticky surface.
- 35 8. An electrical or electronic appliance (10),
comprising a housing with wall parts (12, 13, 14)
and electrical and/or electronic components which
are arranged therein and act as a heat source,
wherein a thermally conductive mat (3) as claimed

5 9. The appliance as claimed in claim 8, wherein at
least some of the components are mounted on a
circuit board (15).

10

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[illegible][illegible]



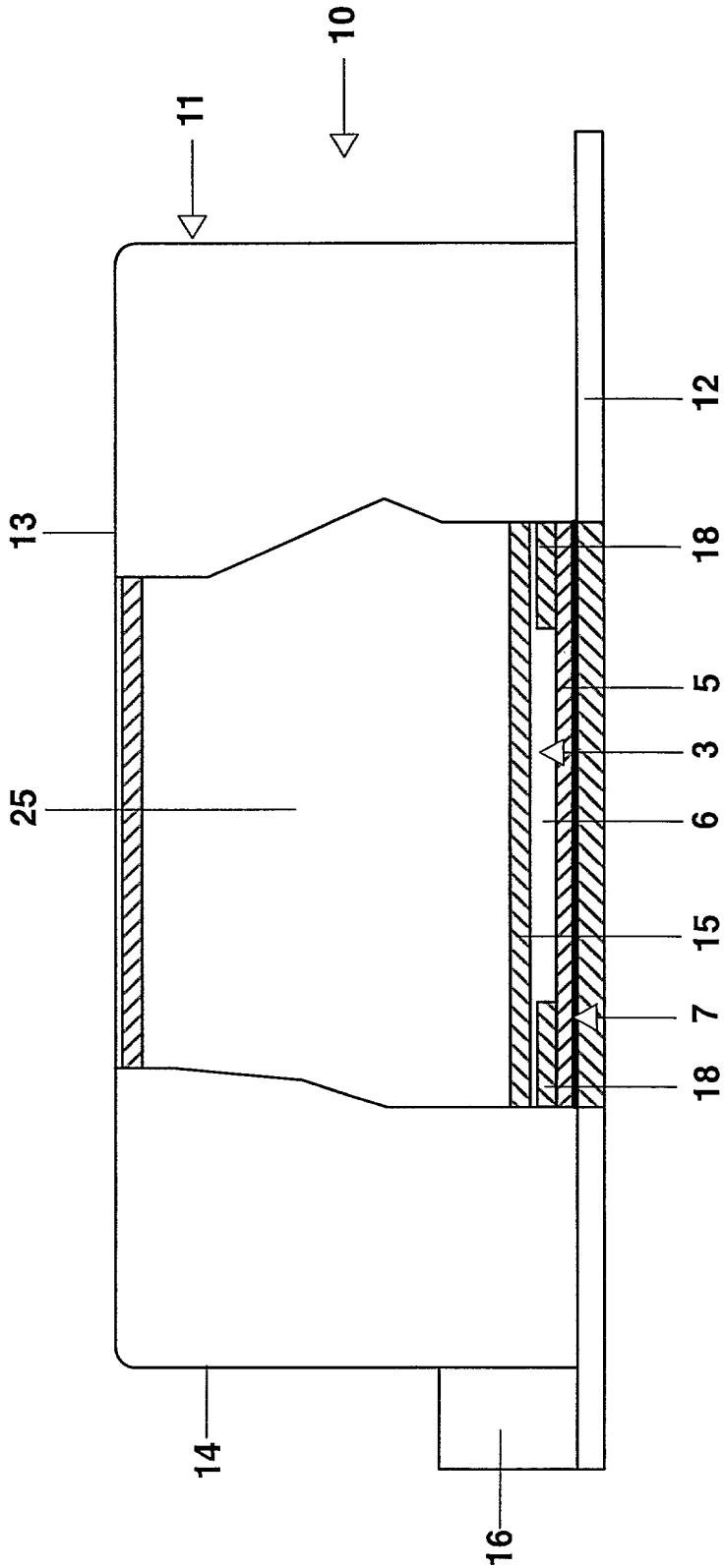


FIG. 2

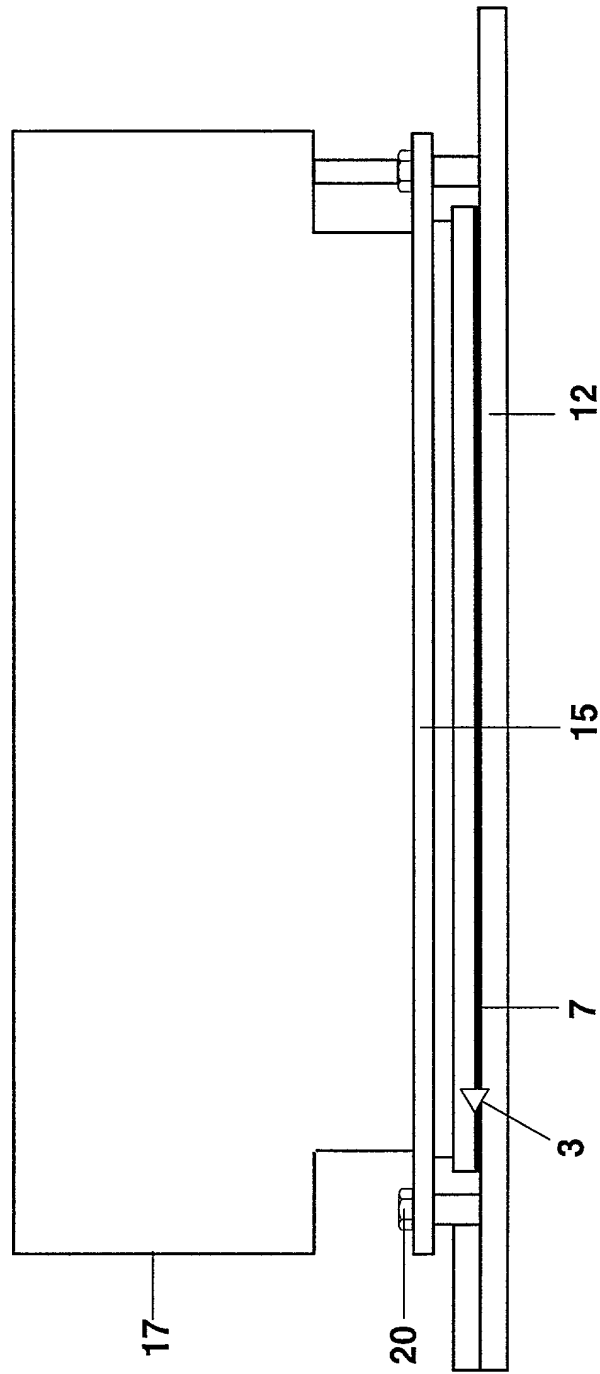


FIG. 3

APPLICATION FOR UNITED STATES LETTERS PATENT

DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I declare that:

my residence, post office address and citizenship are as stated next to my name; I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the invention which is described and which is claimed in the specification, entitled:

Thermally conductive inlay mat for electrical and electronic appliances

The specification is attached hereto.

I have reviewed and understand the contents of said specification, including claims.

I acknowledge the duty to disclosure information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulation, Section 1.56(a).

I claim foreign priority benefits under Title 35 United States Code, Section 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application(s) for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

COUNTRY	APPLICATION NUMBER	DATE (month, day, year)	PRIORITY CLAIMED
Fed. Rep. Germany	198 41 037.9	September 9, 1998	YES <u>X</u> No <u> </u>
Fed. Rep. Germany	298 17 185.6	September 24, 1998	YES <u>X</u> No <u> </u>

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I appoint the following to prosecute this application and to transact all business in the U.S. Patent & Trademark Office connected therewith: Carlo S. Bessone, Reg. No. 30,547; Robert F. Clark, Reg. No. 33,853; William E. Meyer, Reg. No. 30,719; and William H. McNeill, Reg. No. 24,426.

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Sign: <i>F. Forster</i> Type: Franz FORSTER	Date: <i>19.07.99</i> Citizen of: Fed. Rep. of Germany	Am Bahnsteig 1 C D-85614 Kirchseeon Federal Republic of Germany
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